

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Yukinobu Murao	07/25/2008
Akira Kumagai	07/16/2008
Yoichiro Numasawa	07/16/2008
RECEIVING PARTY DATA	
Name:	Canon Anelva Corporation
Street Address:	2-5-1, Kurigi, Asao-ku
City:	Kawasaki-shi, Kanagawa-ken
State/Country:	JAPAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12128465
CORRESPONDENCE DATA	
Fax Number:	(212)218-2200
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	2122182100
Email:	lyu-jahnes@fchs.com
Correspondent Name:	Lock See Yu-Jahnes
Address Line 1:	Fitzpatrick, Cella, Harper & Scinto
Address Line 2:	30 Rockefeller Plaza
Address Line 4:	New York, NEW YORK 10112
ATTORNEY DOCKET NUMBER:	03595.000500.
NAME OF SUBMITTER:	Lock See Yu-Jahnes
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CH \$40.00 12128465

PATENT

500613361

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P208-0389US

JOINT

(AFTER APPLICATION FILED)

ASSIGNMENT

FOR VALUE RECEIVED, WE **Yukinobu Murao, Akira Kumagai and
Yoichiro Numasawa**

citizens of **Japan**

hereby sell, assign, transfer and convey unto **CANON ANELVA CORPORATION**

a corporation of **Japan**

having a place of business at **2-5-1, Kurigi, Asao-ku, Kawasaki-shi, Kanagawa-ken,
Japan**

its successors, assigns and legal representatives (hereinafter called the "Assignee"), the entire right, title, and interest, for all countries, in and to certain inventions relating to

**NANOSILICON SEMICONDUCTOR SUBSTRATE MANUFACTURING METHOD
AND SEMICONDUCTOR CIRCUIT DEVICE USING NANOSILICON
SEMICONDUCTOR SUBSTRATE MANUFACTURED BY THE METHOD**

and described in an application for Letters Patent of the United States executed by us, and filed on **May 28, 2008 as Application No. 12/128,465**, and in and to said application, and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues and extensions thereof, and all applications for Letters Patent or other grants of protection of proprietary rights including, but not limited to, inventor's certificate, utility model, utility certificate, patent of importation, registration of patent and industrial design registration which may be filed, and which may be granted, upon said inventions in any countries or regions foreign to the United States, and all reissues, renewals and extensions thereof; and we hereby authorize and request the Commissioner for Patents and Trademarks of the United States, and all officials of countries or regions foreign to the United States having authority to do so, to issue all such Letters Patent or other grants of protection upon said inventions to the Assignee or to such nominees as it may designate.

AND we authorize and empower the said Assignee or nominees to invoke and claim for any application for such Letters Patent or other grants of protection for said inventions filed by it or them, the benefit of the right of priority provided by the international Convention for the Protection of Industrial Property, as amended, or by a convention which may henceforth be substituted for it, and to invoke and claim such right of priority without further written or oral authorization from us.

AND we hereby consent that a copy of this assignment shall be deemed a full and formal equivalent of any assignment, consent to file or like document which may be required in any country or region for any purpose and more particularly in proof of the right of the said Assignee or nominees to claim the aforesaid benefit of the right of priority provided by the International Convention for the Protection of Industrial Property, as amended, or by any convention which may henceforth be substituted for it.

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AND we hereby covenant that we have the full right to convey the entire right, title and interest herein assigned and that we have not executed and will not execute any agreement in conflict herewith.

AND we hereby covenant and agree that we will communicate to said Assignee or nominees all facts known to us pertaining to said inventions, and testify in all legal proceedings, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and declarations and in general perform all lawful acts necessary or proper to aid said Assignee or nominees in obtaining, maintaining, and enforcing all lawful patent or other grants of protection of said inventions in any and all countries and regions.

By: Yukinobu Murao
Yukinobu Murao

Date: July 25, 2008

By: Akira Kumagai
Akira Kumagai

Date: July 16 / 2008

By: Yoichiro Numasawa
Yoichiro Numasawa

Date: July 16 / 2008